



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS740S2		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA001103274							
<b>Package</b>		PG-DSO-20-59		<b>Weight*</b>		501.30 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.627	2.52	2.52	25188	25188	
leadframe	non noble metal	zinc	7440-66-6	0.169	0.03		338		
	inorganic material	phosphorus	7723-14-0	0.042	0.01		84		
	non noble metal	iron	7439-89-6	3.388	0.68		6759		
	non noble metal	copper	7440-50-8	137.580	27.44	28.16	274447	281628	
wire	noble metal	gold	7440-57-5	3.329	0.66	0.66	6640	6640	
encapsulation	organic material	carbon black	1333-86-4	0.670	0.13		1336		
	plastics	epoxy resin	-	30.812	6.15		61463		
	inorganic material	silicondioxide	60676-86-0	303.427	60.53	66.81	605281	668080	
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5478	5478	
plating	noble metal	silver	7440-22-4	3.476	0.69	0.69	6935	6935	
glue	plastics	epoxy resin	-	0.531	0.11		1059		
	noble metal	silver	7440-22-4	2.502	0.50	0.61	4992	6051	
*deviation	< 10%					Sum in total:	100,00		1000000

### Important Remarks:

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